

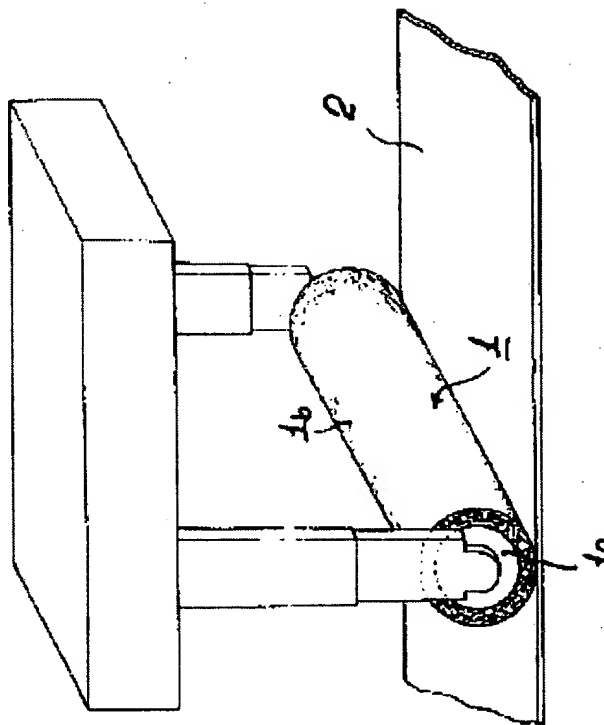
## PLATING METHOD

**Patent number:** JP57171690  
**Publication date:** 1982-10-22  
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**Classification:**  
- **International:** C25D5/06  
- **European:**  
**Application number:** JP19810056132 19810413  
**Priority number(s):**

### Abstract of JP57171690

**PURPOSE:** To easily perform desired plating to the surface of a substance to be treated, by pressing the surface of the substance to be treated, by use of a roller to which a plating liquid and electrically conducted, and also turning and moving it.

**CONSTITUTION:** Plating is performed by feeding power to a roller 1 consisted of a roller core 1a consisting of a metal, carbon, etc., and a solution impregnating material 1b wound round its outside circumference to necessary thickness, to which a plating liquid has been fed, turning this roller 1, pressing the surface of a substance to be treated 2, and moving the roller 1. The impregnating material 1b of said roller 1 is impregnated with a plating liquid obtained by ionizing a desired metal. Also, to the roller 1 side and the substance to be treated 2 side, the positive pole side of a DC power supply and the negative pole side are connected respectively, and plating is performed in electrically-conducting. As a result, desired plating can be performed easily to the surface of the substance to be treated, by only making the roller contact with the substance to be treated, and a plating liquid tank is not required, therefore, the quantity of the plating liquid can be saved.



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